

Title (en)
METHOD FOR GROUNDING A HIGH VOLTAGE ELECTRODE

Title (de)
VERFAHREN ZUM ERDEN EINER HOCHSPANNUNGSELEKTRODE

Title (fr)
PROCÉDÉ DE MISE À LA TERRE D'UNE ÉLECTRODE HAUTE TENSION

Publication
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Application
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Abstract (en)
[origin: WO2007112599A1] The invention relates to an arrangement comprising a high voltage electrode (1) and a process vessel (2) that is associated with said high voltage electrode (1). The high voltage electrode (1) and the process vessel (2) can be placed relative to one another in such a way that the operational end (5) of the high voltage electrode (1) is immersed in the process vessel (2) in an operating position while being disposed outside the process vessel (2) in an off position. The arrangement further comprises a grounding device (3) which is embodied so as to automatically enter in contact with the operational end (5) of the electrode in order to ground the high voltage electrode (1) when the same is placed in the off position. The inventive arrangement makes it possible to create electrodynamic fragmentation systems in which the high voltage electrode (1) is automatically and reliably grounded when the operational end (5) thereof becomes accessible while the grounding can actually be seen, thus significantly improving personnel safety.

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